

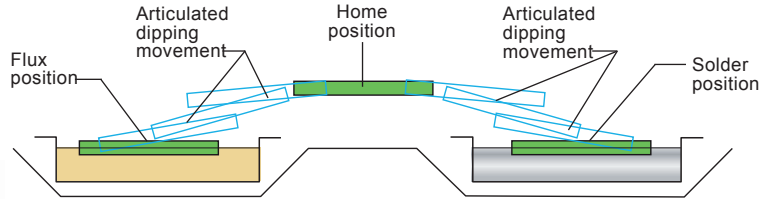
Dip Solder Machines & Dip Solder Pots



LEAD FREE



Using the Big Dipper membrane keypad, the operator can control solder temperature, preheat time, solder dip time and store the program number.



Big Dipper Process

Big Dipper™

Semi-automatic Model GW-BD
Lead Free Model: GW-BD-HT

Features

The Big Dipper semi-automatic soldering system completely solders entire PC boards. The microprocessor controller makes consistent and high quality soldering easy by prompting the operator, with audible beeps, throughout the entire process.

- Articulated dipping movement prevents trapping of air bubbles
- 3 stage timed process includes: flux cycle, preheat cycle, and solder cycle
- Microprocessor control with LCD display
- 12 menu storage
- Flux station with flux drain
- Stainless steel solder pot
- Pallet with adjustable titanium fingers hold PCBs

Big Dipper Specifications

Power	120 VAC, 60 Hz, 20 A optional 220 VAC, 50/60 Hz, 10 A
Max solder temp	350°C (662°F)
Solder capacity	approx. 50 lbs (23Kg)
Max board size	8" x 11.375" (203 x 290 mm)
Dimensions	31" x 25.25" x 24.5" (787 x 641 x 622 mm)
Warm-up time	approx. 50 min
Weight	62 lbs empty (28Kg), 112 lbs (50 Kg) with solder



Little Dipper™

Model GW-LD
Lead Free Model: GW-LD-HT

Features

The Little Dipper solder pot can be used for a variety of solder dipping applications.

- Digital closed loop temperature control
- Stainless steel solder pot
- Solder surface area: 9.375" x 13" (238 x 330 mm)

Little Dipper Specifications

Power	120 VAC, 60 Hz, 20 A optional 220 VAC, 50/60 Hz, 10 A
Max solder temperature	350°C (662°F)
Solder capacity	approx. 50 lbs (23Kg)
Solder pot size	9.375" x 13.0" x 1.75" (238 x 330 x 44 mm)
Dimensions	16.25" x 17.5" x 9" (413 x 445 x 230 mm)
Warm-up time	Approx. 50 min
Weight	28 lbs empty (13Kg), 78 lbs (35 Kg) with solder